

**4-PIN SOP, 1.1 pF LOW OUTPUT CAPACITANCE
1-ch Optical Coupled MOS FET****DESCRIPTION**

The PS7200R-1A is a low output capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low $C \times R$, low output capacitance, and low off-state leakage current.

FEATURES

- Low $C \times R$ ($C \times R = 11 \text{ pF} \cdot \Omega$)
- Low output capacitance ($C_{\text{out}} = 1.1 \text{ pF TYP.}$)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage ($BV = 1\,500 \text{ Vr.m.s.}$)
- Low offset voltage
- Ordering number of taping product: PS7200R-1A-E3, E4, F3, F4

APPLICATIONS

- Measurement equipment

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

Technical drawings of the LED module:

- Top View:** Shows the square package with four pins (1, 2, 3, 4) and a circular LED die. The dimensions are:
 - Pin 1: LED Anode
 - Pin 2: LED Cathode
 - Pin 3: MOS FET
 - Pin 4: MOS FET
- Side View:** Shows the package height and pin dimensions. The dimensions are:
 - Package height: $2.05^{+0.08}_{-0.05}$
 - Pin height: $0.05^{+0.08}_{-0.05}$
 - Pin width: $0.40^{+0.10}_{-0.05}$
 - Pin pitch: $0.25(M)$
- Bottom View:** Shows the package footprint and pin dimensions. The dimensions are:
 - Package width: 7.0 ± 0.3
 - Package length: 4.4
 - Pin width: $0.15^{+0.10}_{-0.05}$
 - Pin pitch: 0.5 ± 0.3

The diagram shows a rectangular marking box containing the text "NEC", "200R", and "001". A black dot is located at the bottom left corner of the box. An arrow points from the text "No.1 pin Mark" to this dot. To the right of the box, two arrows point to the "200R" and "001" respectively, with labels "Type Number*1" and "Assembly Lot".

*1 Applicable type numbers are underlined below

PS7200R-1A

000 ←

Week Assembled
Year Assembled
(Last 1 Digit)

Rank Code

Nothing	Ink marking
N	Laser marking

ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS7200R-1A	4-pin SOP	Magazine case 100 pcs	PS7200R-1A
PS7200R-1A-E3		Embossed Tape 900 pcs/reel	
PS7200R-1A-E4			
PS7200R-1A-F3		Embossed Tape 3 500 pcs/reel	
PS7200R-1A-F4			

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I _F	50	mA
	Reverse Voltage	V _R	5.0	V
	Power Dissipation	P _D	50	mW
	Peak Forward Current ^{*1}	I _{FP}	1	A
MOS FET	Break Down Voltage	V _L	40	V
	Continuous Load Current	I _L	120	mA
	Pulse Load Current ^{*2} (AC/DC Connection)	I _{LP}	240	mA
	Power Dissipation	P _D	200	mW
Isolation Voltage ^{*3}		BV	1 500	Vr.m.s.
Total Power Dissipation		P _T	250	mW
Operating Ambient Temperature		T _A	−40 to +85	°C
Storage Temperature		T _{stg}	−40 to +100	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output

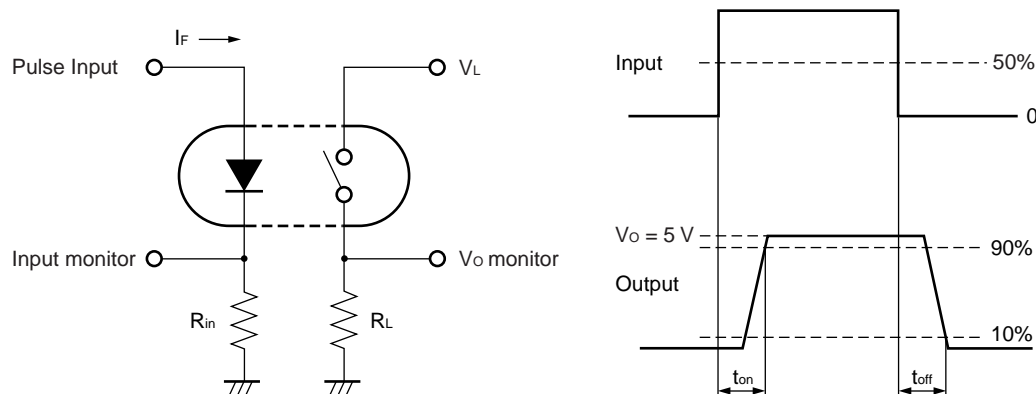
RECOMMENDED OPERATING CONDITIONS ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$		1.2	1.4	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5.0	μA
MOS FET	Off-state Leakage Current	I_{Leak}	$V_D = 40\text{ V}$			10	nA
	Output Capacitance	C_{out}	$V_D = 0\text{ V}$, $f = 1\text{ MHz}$		1.1		pF
Coupled	LED On-state Current	I_{Fon}	$I_L = 120\text{ mA}$			2.0	mA
	On-state Resistance	R_{on1}	$I_F = 10\text{ mA}$, $I_L = 10\text{ mA}$		10	12.5	Ω
		R_{on2}	$I_F = 10\text{ mA}$, $I_L = 120\text{ mA}$, $t \leq 10\text{ ms}$		11	14	
	Turn-on Time ^{*1,2}	t_{on}	$I_F = 10\text{ mA}$, $V_O = 5\text{ V}$, $R_L = 500\text{ }\Omega$, $PW \geq 10\text{ ms}$		0.03	0.5	ms
	Turn-off Time ^{*1,2}	t_{off}			0.3	1.0	
	Isolation Resistance	$R_{\text{I-O}}$	$V_{\text{I-O}} = 1.0\text{ kV}_{\text{DC}}$	10^9			Ω
	Isolation Capacitance	$C_{\text{I-O}}$	$V = 0\text{ V}$, $f = 1\text{ MHz}$		0.3		pF

***1 Test Circuit for Switching Time**

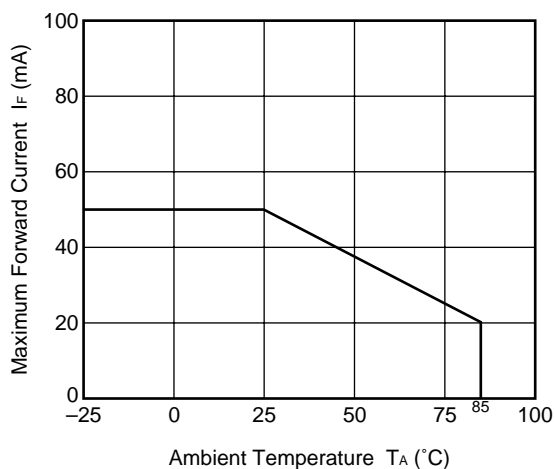


***2 The turn-on time and turn-off time are specified as input-pulse width $\geq 10\text{ ms}$.**

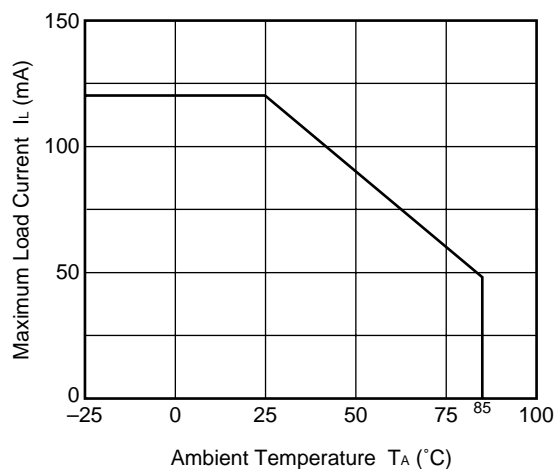
Be aware that when the device operates with an input-pulse width of under 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

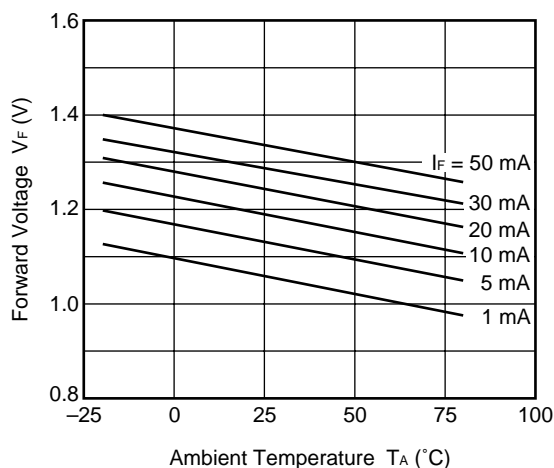
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



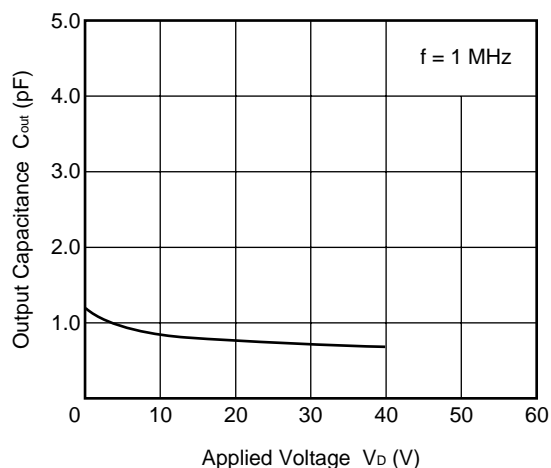
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



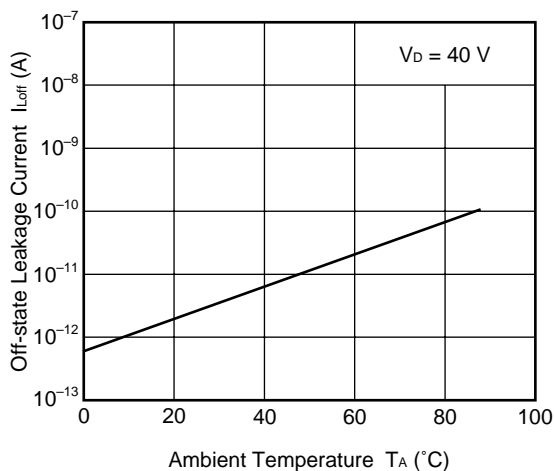
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



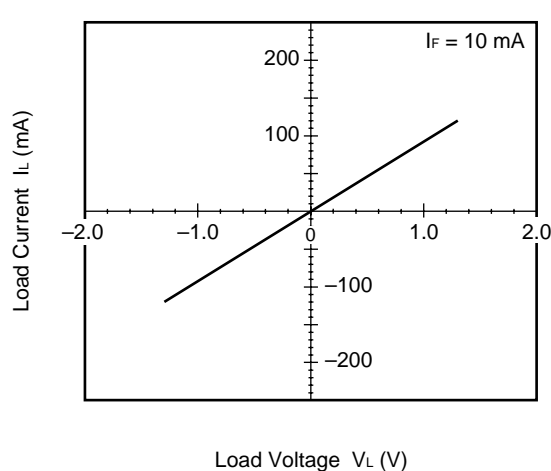
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



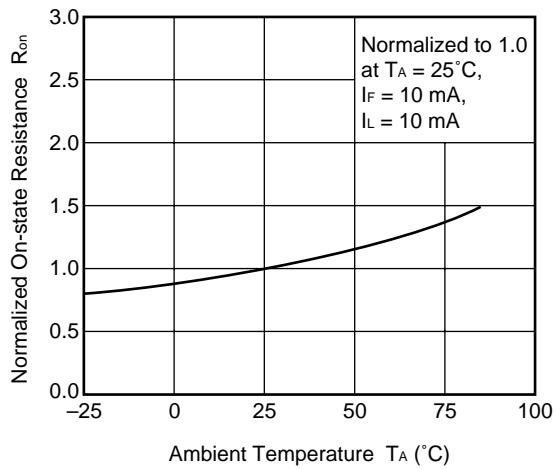
OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



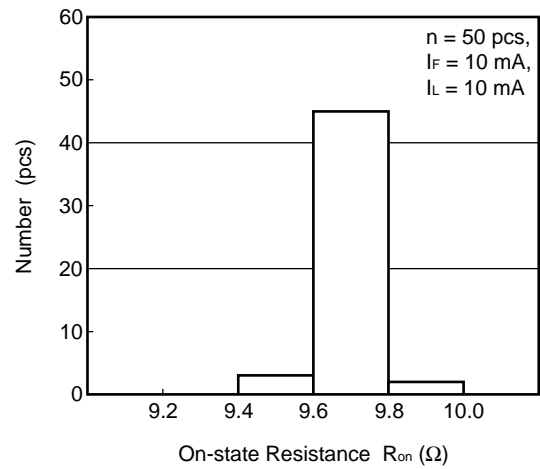
LOAD CURRENT vs. LOAD VOLTAGE



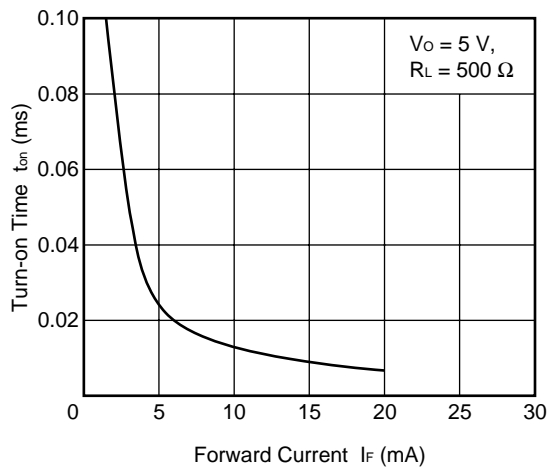
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



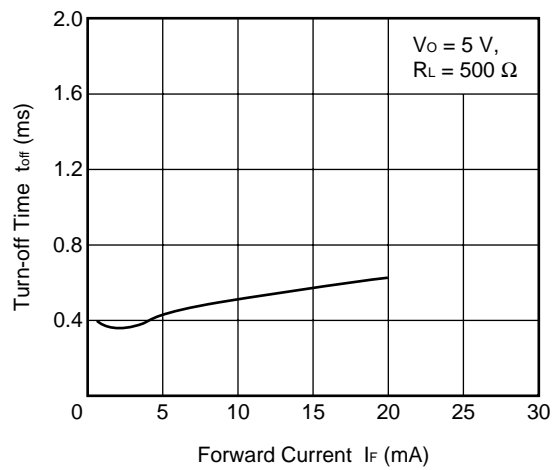
ON-STATE RESISTANCE DISTRIBUTION



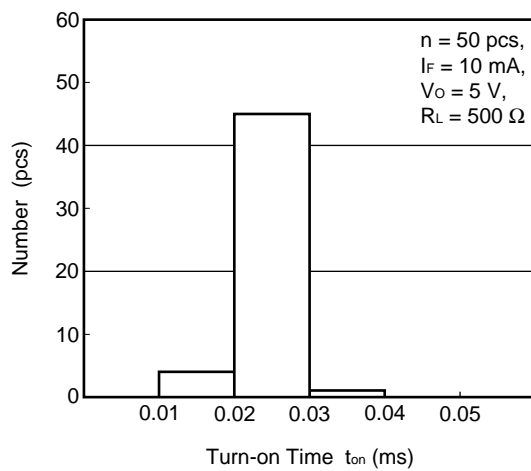
TURN-ON TIME vs. FORWARD CURRENT



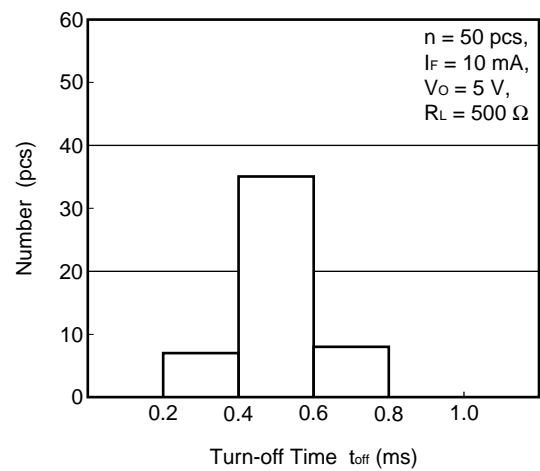
TURN-OFF TIME vs. FORWARD CURRENT

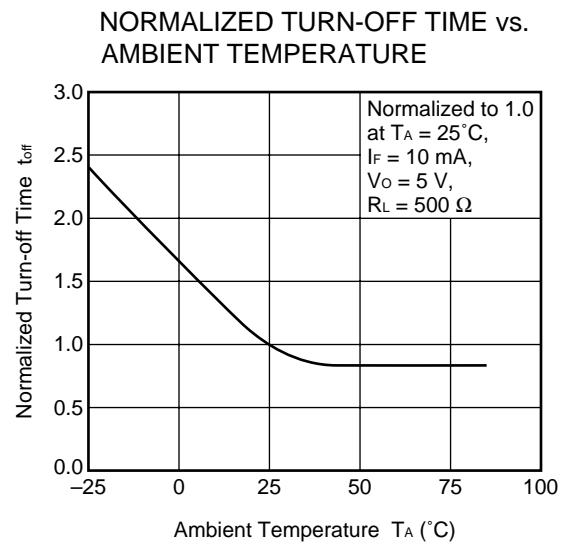
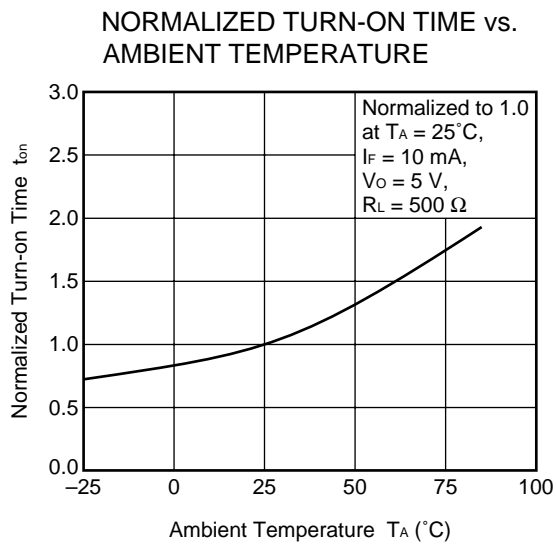


TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION

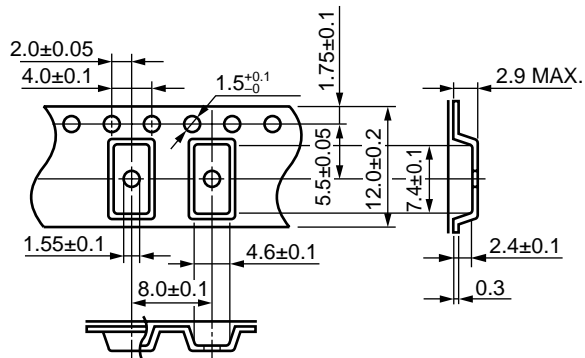




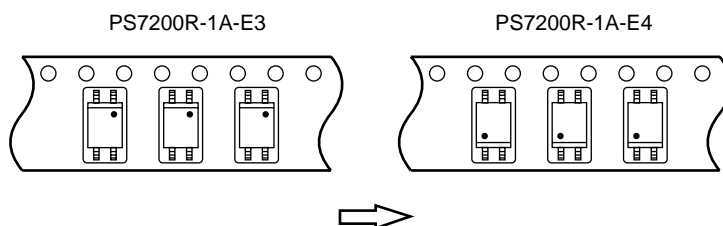
Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (UNIT: mm)

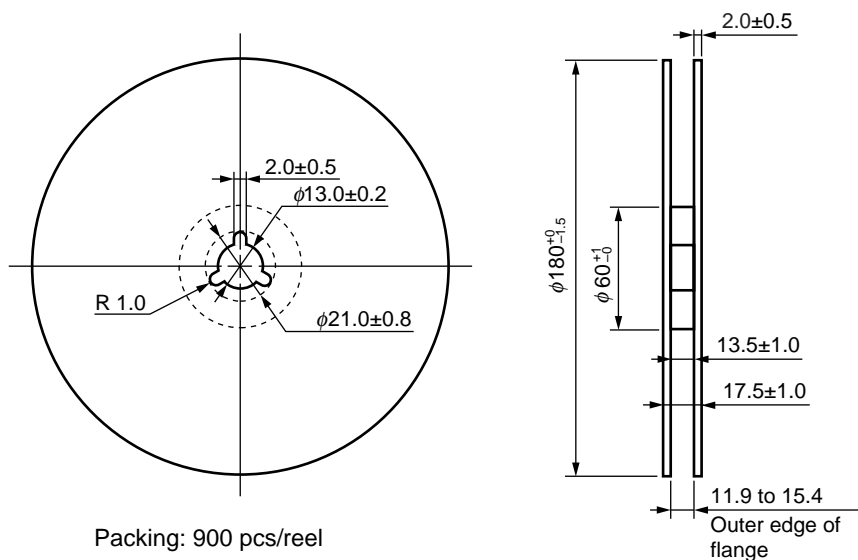
Outline and Dimensions (Tape)



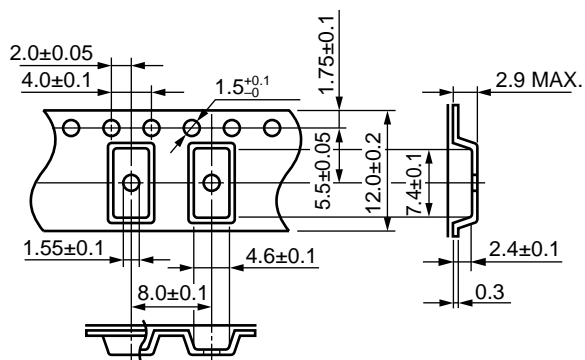
Tape Direction



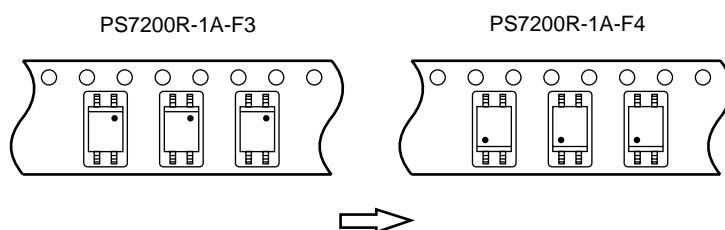
Outline and Dimensions (Reel)



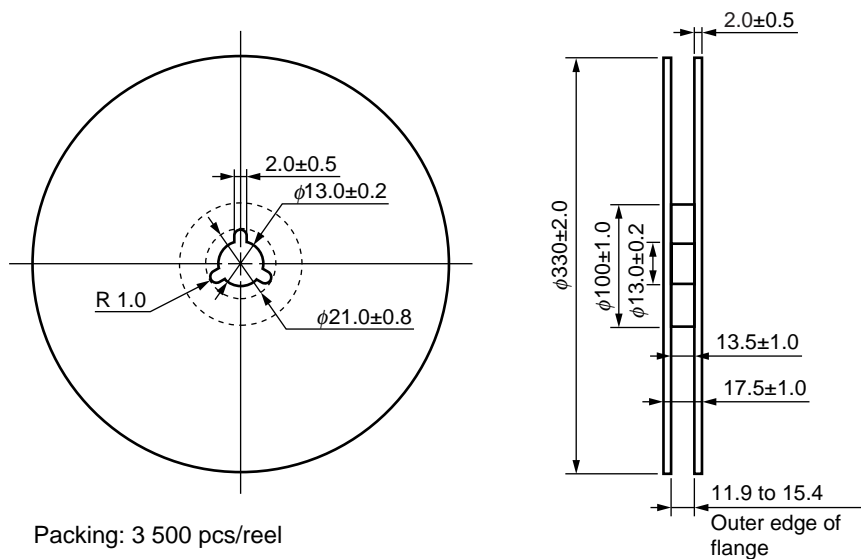
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

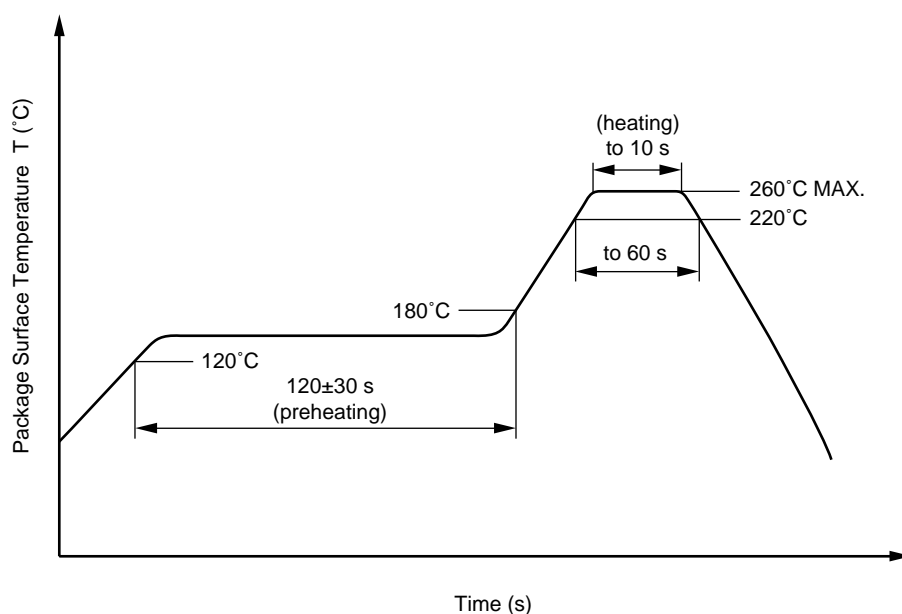


★ RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
 - Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

SAFETY INFORMATION ON THIS PRODUCT

<div data-bbox="188 277 280 304">Caution</div> <div data-bbox="300 277 448 300">GaAs Products</div>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► For further information, please contact

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